

## PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1  
 Stylesheet Version v1.2

EPAS ID: PAT2819508

<b>SUBMISSION TYPE:</b>	NEW ASSIGNMENT
<b>NATURE OF CONVEYANCE:</b>	ASSIGNMENT
<b>CONVEYING PARTY DATA</b>	
<b>Name</b>	<b>Execution Date</b>
SHINJI EDA	01/05/2011
HIDEKI ISONO	01/05/2011
<b>RECEIVING PARTY DATA</b>	
<b>Name:</b>	HOYA CORPORATION
<b>Street Address:</b>	7-5, NAKA-OCHIAI 2-CHOME
<b>City:</b>	SHINJUKU-KU, TOKYO
<b>State/Country:</b>	JAPAN
<b>Postal Code:</b>	161-8525
<b>PROPERTY NUMBERS Total: 1</b>	
<b>Property Type</b>	<b>Number</b>
<b>Application Number:</b>	14255755
<b>CORRESPONDENCE DATA</b>	
<b>Fax Number:</b>	(202)293-0445
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent via US Mail.</i>	
<b>Phone:</b>	2022930444
<b>Email:</b>	mailpto@giplaw.com
<b>Correspondent Name:</b>	GLOBAL IP COUNSELORS, LLP DAVID TARNOFF
<b>Address Line 1:</b>	1233 20TH STREET, NW, SUITE 700
<b>Address Line 2:</b>	SUITE 700
<b>Address Line 4:</b>	WASHINGTON, DISTRICT OF COLUMBIA 20036-2680
<b>ATTORNEY DOCKET NUMBER:</b>	HC-US093123A
<b>NAME OF SUBMITTER:</b>	JOSEPH J. BUCZYNSKI
<b>SIGNATURE:</b>	/Joseph J. Budzynski/
<b>DATE SIGNED:</b>	04/17/2014
<b>Total Attachments: 1</b>	
source=HC-US093123A_Assignment#page1.tif	

# ASSIGNMENT

[Executed in Japan]

WHEREAS, Shinji EDA, a citizen of Japan having a mailing address at c/o HOYA Corporation, 7-5, Naka-Ochiai 2-Chome, Shinjuku-ku, Tokyo 161-8525, Japan,

Hideki ISONO, a citizen of Japan having a mailing address at c/o HOYA Corporation, 7-5, Naka-Ochiai 2-Chome, Shinjuku-ku, Tokyo 161-8525, Japan,

hereinafter referred to as the Assignor(s), have invented certain new and useful improvements in

**GLASS SUBSTRATE FOR MAGNETIC DISK AND MANUFACTURING METHOD THEREOF**

for which the Assignor(s) have executed an Application for United States Letters Patent

(X) Executed concurrently herewith

( ) Serial No. \_\_\_\_\_ Filed \_\_\_\_\_.

AND WHEREAS, HOYA CORPORATION having its principal place of business at

7-5, Naka-Ochiai 2-Chome, Shinjuku-ku, Tokyo 161-8525, Japan (hereinafter referred to as the Assignee), is desirous of acquiring the entire right, title, and interest in and to said invention and said Application and in and to any Letters Patent or Patents, United States or foreign as indicated below, to be obtained therefor and thereon:

NOW, THEREFORE, for good and valuable consideration, the receipt and sufficiency of which is herewith acknowledged, the Assignor(s) sell, assign, and transfer, unto the Assignee, its successors, legal representatives and assigns, the entire right, title, and interest in the United States of America, and in all foreign countries, in, to and under said improvements, and said Application, and all original, divisional, renewal, continuation, substitute, or reissue applications thereof, including the right to sue and recover for any past infringement, and all rights of priority from the filing of said Application; and the Assignor(s) hereby authorize and request the Commissioner of Patents and Trademarks to issue all Letters Patent on said improvements or resulting therefrom to said Assignee herein, as assignee of the entire interest therein, for the sole use and behalf of said Assignee, its successors, and assigns, to the full end of the term or terms for which Letters Patent or Patents may be granted.

Further, the Assignor(s) and their legal representatives, heirs, and assigns do hereby agree and covenant without further remuneration that they will communicate to said Assignee, its successors, legal representatives and assigns, any facts known to them respecting said improvements whenever requested, and will testify in any interferences or other legal proceeding in which any of said applications or Letters Patent may become involved, sign all lawful papers, execute and deliver all divisional, continuing, reissue and other applications for Letters Patent on said improvements and all assignments thereof to said Assignee or its legal representatives, successors, or assigns, make all rightful oaths and generally do everything necessary to assist said Assignee, its successors, legal representatives and assigns, to obtain and enforce proper patent protection for said improvements in the U.S. and said countries, the expenses incident to said applications to be borne and paid by said assignee.

The undersigned hereby grants the firm of **Global IP Counselors, LLP** the power to insert in this Assignment any further identification which may be necessary or desirable to comply with the rules of the U.S. Patent and Trademark Office for recordation of this Assignment.

IN TESTIMONY WHEREOF, the undersigned Assignor(s) have affixed their signatures.

Shinji EDA Date: 05-Jan-11 Hideki ISONO Date: 05-Jan-2011